OVERVIEW OF CONFERENCE PROGRAM

Note: The information is only for your reference. The final conference schedule shall prevail on the date of conference.

Date	**Time**	**Junior Ballroom I, 2F**				**Junior Ballroom III, 2F**			
Aug. 5th	08:30-11:50	PDC 1-2				PDC 6-7			
	11:50-13:00	***Break***							
	13:00-17:50	PDC 3-5				PDC 8-10			
	19:00-21:00	***Football Game***							
Date	**Time**	**Grand Ballroom, 3F**							
Aug. 6th	08:30-12:00	*OPENING CEREMONY & PLENARY TALK 1-6*							
	12:00-13:30	***Lunch***							
	Time	**Room 1**	**Room 2**	**Room 3**	**Room 4**	**Room 5**	**Room 6**	**Room 7**	**Room 8**
	13:30-15:20	Session A1	Session B1	Session C1	Session D1	Session E1	Session F1	Session G1	Session H1
	15:20-16:00	*Poster Session A*							
	16:00-18:50	Session A2	Session B2	Session C2	Session D2	Session E2	Session F2	Session G2	
	19:00-21:00	***Welcome Dinner***							
Date	**Time**	**Grand Ballroom, 3F**							
Aug. 7th	08:30-12:30	*PLENARY TALK 7-14*							
	12:30-13:30	***Lunch***							
	Time	**Room 1**	**Room 2**	**Room 3**	**Room 4**	**Room 5**	**Room 6**	**Room 7**	**Room 8**
	13:30-15:20	Session A3	Session B3	Session C3	Session D3	Session E3	Session F3	Session G3	Session H2
	15:20-16:00	*Poster Session B*							
	16:00-18:40	Session A4	Session B4	Session C4	Session D4	Session E4	Session F4	Session G4	Session H3
End									

OVERVIEW OF PROFESSIONAL DEVELOPMENT COURSE

Tuesday, August 5th, 2025, 08:30-17:50 2F, Junior Ballroom I & III

Time	Junior Ballroom I	Junior Ballroom III
Chair	***Dr. Qidong WANG,*** *IMECAS, China*	***Prof. Nan WANG,*** *Shanghai University, China*
08:30-10:00	**PDC 1-Advanced Packaging for High Performance Computing** ***Dr. Daquan YU*** *Professor at Xiamen University, China; Chairman of Xiamen Sky Semiconductor Co., Ltd., China*	**PDC 6-Advanced Substrates for Chiplets and Heterogeneous Integration** ***Dr. John H Lau*** *Chief Scientist of Unimicron Technology Corporation, Taiwan, China*
10:00-10:20	***Break***	
10:20-11:50	**PDC 2-Mechanics and Reliability of Lead-Free Solder Joints** ***Prof. Jeffrey C. Suhling*** *Auburn University, USA*	**PDC 7-Packaging of MEMS and More** ***Prof. Shuji Tanaka*** *Department of Robotics, Graduate School of Engineering, Tohoku University, Japan*
11:50-13:00	***Break***	
Chair	***Prof. Wei WANG,*** *Peking University, China*	***Prof. Luqiao YIN,*** *Shanghai University, China*
13:00-14:30	**PDC 3-Analysis of Fracture and Delamination in Microelectronic Packages** ***Prof. Andrew Tay*** *Department of Electrical and Computer Engineering, National University of Singapore, Singapore*	**PDC 8-Innovations in Advanced Packaging Technology** ***Dr. Wei Koh*** *Founder of Pacrim Technology Irvine, CA, USA*
14:30-14:40	***Break***	
14:40-16:10	**PDC 4-MEOL Design and Process Consideration for Heterogeneous Integrated Package and Substrate** ***Prof. Gu-Sung Kim*** *Kangnam University, Yongin, S Korea*	**PDC 9- Quantum Mechanics and Molecular Dynamics and Their Applications in Electronic Manufacturing** ***Prof. Sheng LIU*** *Academician of Chinese Academy of Sciences, Dean of the School of Integrated Circuits, Wuhan University, China* ***Prof. Yuzheng GUO*** *Dean of School of Power and Mechanical Engineering, Wuhan University, China*
16:10-16:20	***Break***	
16:20-17:50	**PDC 5-Nano Materials and Polymer Composites for Electronic Packaging** ***Dr. Daniel LU*** *Vice President, Henkel Corporation*	**PDC 10-High Reliability Soldering in Semiconductor Packaging** ***Dr. Ning-Cheng LEE*** *Founder of ShinePure Hi-Tech, China*
19:00-21:00	***Football Game***	

OVERVIEW OF PLENARY TALKS

Wednesday, August 6th, 2025, 08:30-12:00 3F, Grand Ballrroom

Plenary Talks I	
OPENING CEREMONY ***Chair: Prof. Kouchi ZHANG, Delft University, the Netherlands***	
08:30-08:45	**Greeting** ***Prof. Tianchun YE,*** *Chair of ICEPT, China* ***Prof. Jianhua ZHANG,*** *Vice President of Shanghai University, China* ***Prof. Jeffrey C. Suhling,*** *IEEE EPS President Elect, USA*
08:45-09:25	**CP Wong Global Electronic Packaging Award** ***Master of Ceremony: Prof. Ricky LEE, Dean of Systems Hub, HKUST(GZ), China***
	From SMT to Hybrid Bonding: 43 Years in Packaging ***Dr. John H Lau*** *Chief Scientist of Unimicron Technology Corporation, Taiwan, China*
	Heterogeneous Integration, From Advanced Materials to Novel Devices ***Dr. René Pgelma*** *Senior Principal Engineer, Nexperia B.V.*
09:25-09:55	**Effects of Aging on the Reliability of Electronic Products Incorporating Lead Free Solders** ***Prof. Jeffrey C. Suhling*** *Quina Professor and Department Chair, Department of Mechanical Engineering, and Center for Advanced Vehicle and Extreme Environment Electronics (CAVE^3), Auburn University, USA*
09:55-10:25	**Multi Field Cross Scale Collaborative Design Methods and Technologies for Chip Manufacturing and Integration** ***Prof. Sheng LIU*** *Academician of Chinese Academy of Sciences, Dean of the School of Integrated Circuits, Wuhan University, China*
10:25-10:50	***Tea Break & Networking***
Chair: Prof. Shuji Tanaka, Department of Robotics, Graduate School of Engineering, Tohoku University, Japan	
10:50-11:20	**From DIP to MIP: 40 Years in Semiconductor Packaging** ***Prof. Kees Beenakker*** *Delft University of Technology, the Netherlands*
11:20-11:50	**Heterogeneous Integration Technology with High Density Bump for Silicon-drived Microdisplays** ***Prof. Jianhua ZHANG*** *Vice President of Shanghai University, China*
12:00-13:30	***Lunch***

OVERVIEW OF ORAL PRESENTATION SESSIONS

Wednesday, August 6th, 2025, 13:30-18:50

Time	Room 1	Room 2	Room 3	Room 4	Room 5	Room 6	Room 7	Room 8
Committee	Advanced Packaging	Packaging Design & Modeling	Interconnection Technologies	Packaging Materials & Processes	Quality & Reliability & Power Electronics	Advanced Manufacturing	Power Electronics	/
13:30-15:20	Session A1-Advanced Integration	Session B1-Thermo-Mechanical Simulation and design	Session C1-Adv. Materials & Proc. for Interconnection	Session D1-Polymer Packaging Materials	Session E1-Process Design Optimization	Session F1-Bonding and Interconnection	Session G1-Power Packaging Design	Session H1-Hybrid Bonding
Chairs	Wei WANG, Shuye ZHANG	Xu LONG, Hongbin SHI	Yunwen WU, STEVEN HE WANG	Chuantong CHEN, Xiaoliang ZENG	Kui LI, Yanwei DAI	Zhaofu ZHANG, Guannan YANG	Hongwen HE, Fengtao YANG	Tadatomo SUGA, Qidong WANG
13:30-13:55（Keynote）	Yu WANG	Shuyang QIN	Thiago Moura	Yik-Yee TAN	Guoguang LU	Xiaojun ZHANG	Jing ZHANG	**(13:30-15:30)** John H Lau Thomas Pleschke Kenny YE Chenxi WANG
13:55-15:20（Oral）	8, 39, 176, 255, 331, 462, 601	47, 76, 207, 334, 369, 430, 513	213, 347, 469, 500, 603, 620, 630	63, 155, 247, 253, 341, 344, 628	7, 34, 72, 322, 476, 618, 549	60, 199, 260, 279, 351, 502, Byeongchan Kim	154, 195, 313, 314, 376, 547, 652	
15:20-16:00	**Poster Session A**							
Committee	Advanced Packaging	Packaging Design & Modeling	Interconnection Technologies	Packaging Materials & Processes	Quality & Reliability	Optoelectronics and New Display	Power Electronics	**(16:00-18:30)** Liyi LI Bin ZHAO Chaoqun REN Renxi JIN Fengwen MU
16:00-18:25	Session A2-Chiplet & FOPLP	Session B2-Thermal Management Simulation	Session C2-3D Interconnection Technologies	Session D2-Metal Packaging Materials	Session E2-Testing & Reliability Simulation	Session F2-Optoelectronic Intergration	Session G2-Power Packaging Materials	
Chairs	Shuying MA, Qian WANG	Jun WANG, Meiying SU	Wangyun LI, Liangxing HU	Zhiquan LIU, Caifu LI	Xiaofeng YANG, Kui LI	Lianqiao YANG, Haohui LONG	Zhaozheng HOU, Jing ZHANG	
16:00-16:25（Keynote）	**Keynote:** **Alex ZHAO** **Yan HUO** **Peng SUN** **Kang ZHANG** **Guoping ZHANG**	Zhenhong ZHONG	Yunwen WU	Yue JIANG	Joonho You	Atsushi Okuno	Yunhui MEI	
16:25-18:05 (Oral)		77, 136, 202, 271, 355, 360, 452, 642	130, 131, 172, 460, 526, 617, 625, 439	**Keynote:** **Chuantong CHEN** 80, 128, 261, 294, 300, 384, 451, 475, 558, 624	**Keynote:** **Cong WANG** 32, 61, 85, 159, 315, 501, 517	**Keynote:** **Steve JIN** 108, 113, 303, 393, 535, 543, 552, 553, 562, 572	50, 59, 188, 244, 356, 362, 400, 435, 445, 489	
18:05-18:50 (Oral)	/	/	/					
19:00-21:00	***Welcome Dinner***							

OVERVIEW OF HYBRID BONDING TECHNOLOGY SESSION

Wednesday, August 6th, 2025, 13:30-18:30 Room 8

Special Session: Hybrid Bonding Technology

Chair: Prof. Tadatomo SUGA, Meisei University, Japan
Dr. Qidong WANG, Institute of Microelectronics of Chinese Academy of Sciences, China

Time	Content
13:30-14:00	**Flip Chip on Glass-Core Substrate with Micropump and Cu-Cu Hybrid Bonding** ***Dr. John H Lau*** *Chief Scientist of Unimicron Technology Corporation, Taiwan, China*
14:00-14:30	**Hybrid Bonding as Crucial Technology for Future Applications** ***Mr. Thomas Pleschke*** *Business Development Manager of EV Group, Austria*
14:30-15:00	**Advancements in Bonding Technologies Enabling Innovations in Device Structures and Packaging Capabilities** ***Dr. Kenny YE*** *Senior Vice President of Piotech, China*
15:00-15:30	**Low-Temperature Hybrid Bonding for Heterogeneous Integration** ***Prof. Chenxi WANG*** *Harbin Institute of Technology, China*
15:30-16:00	**Tea Break & Networking**
16:00-16:30	**Hybrid Bonding Interface Issues** ***Prof. Liyi LI*** *Southeast University, China*
16:30-17:00	**Pushing the Limit of Bonding Accuracy and Throughput** ***Mr. Bin ZHAO*** *CTO of Guangdong iStar Technology Equipment Co., Ltd.(iSTAR), China*
17:00-17:30	**Application of Advanced Bonding Technologies in FEOL Processes** ***Mr. Chaoqun REN*** *General Manager of Wisdom SemiTeC (Jiangsu) Technology Co., Ltd., China*
17:30-18:00	**Interface Engineering for Hybrid Bonding Interconnect** ***Dr. Renxi JIN*** *Research of Institute of Microelectronics, Chinese Academy of Sciences, China*
18:00-18:30	**Advanced Hybrid Bonding Technologies and Applications** ***Dr. Fengwen MU*** *Founder and CEO of iSABers Group Co., Ltd., China*
End	

OVERVIEW OF PLENARY TALKS

Thursday, August 7th, 2025, 08:30-12:30 3F, Grand Ballroom

Plenary Talks II	
OPENING CEREMONY ***Chair: Prof. Johan LIU, Academician of the Royal Swedish Academy of Engineering Sciences, Sweden***	
08:30-09:00	**Recent Advances and Trends in Cu-Cu Hybrid Bonding** ***Dr. John H Lau*** *Chief Scientist of Unimicron Technology Corporation, Taiwan, China*
09:00-09:30	**Advanced Packaging Technology for AI and Power Semiconductors** ***Prof. Katsuaki Suganuma*** *Osaka University, Japan*
09:30-10:00	**Manufacturing Transformation Era: Process Solutions for Wafer and Panel-Level Packaging Driven by Semiconductor Process Technology** ***Dr. Taku Hanna*** *Director, PE-Semiconductor Technology Research Department, Institute of Advanced Technology, Research & Development HQ, ULVAC, Inc., Japan*
10:00-10:30	**The Application and Development of Silicon Photonics and Advanced Packaging Technology** ***Mr. Scott CHEN*** *Vice General Manager of ASE (Advanced Semiconductor Engineering), Taiwan, China*
10:30-10:45	***Tea Break & Networking***
Chair: Prof. Ricky LEE ***Dean of Systems Hub, Hong Kong University of Science and Technology (Guangzhou), China, IEEE Fellow***	
10:45-11:15	**Semiconductor Equipment Supply Chain for FEOL Advanced Packaging** ***Dr. Kitty Pearsall*** *IEEE EPS DL, Independent Consultant, USA*
11:15-11:45	**Low-Temperature Bonding Technology for Heterogeneous Integration and Advances in Sensors and Electronic Devices** ***Prof. Eiji Higurashi*** *Tohoku University, Japan*
11:45-12:15	**The Challenges and New Developments on TSV Etch Applications** ***Dr. Guorong LI*** *Vice General Manager of the First Etching Business Unit, NAURA, China*
12:15-12:30	**The Role of the IEEE Electronics Packaging Society in the Development of Professionals and Students in Electronics Packaging** ***Prof. Andrew Tay*** *IEEE EPS Program Director, National University of Singapore*
12:30-13:30	***Lunch***

OVERVIEW OF ORAL PRESENTATION SESSIONS

Thursday, August 7th, 2025, 13:30-18:40

Time	**Room 1**	**Room 2**	**Room 3**	**Room 4**	**Room 5**	**Room 6**	**Room 7**	**Room 8**
Committee	Advanced Packaging	Packaging Materials & Processes	Packaging Design & Modeling	Advanced Manufacturing	Packaging Design & Modeling	Quality & Reliability	Packaging Materials & Processes	/
13:30-15:20	Session A3-Hybrid Bonding Technology	Session B3-Ceramic and Composite Pkg. Materials	Session C3-Electromagnetic Simulation	Session D3-Evaluation and Measurement	Session E3-Emerging Simulation Technologies	SessionF3-Failure Analysis	Session G3-Packaging Materials	SessionH3-ICEP Session
Chairs	Kai ZHAO, Ziyu LIU	Tao HANG, Yujie LI	Jun LI, Xingchang WEI	Fulong ZHU, Zili ZHANG	Daoguo YANG, Pei CHEN	Chuantao HOU, Sha XU	Yi ZHONG, Zhengwei FAN	JunshaWANG, Yasuhiro Morikawa
13:30-13:55（Keynote）	Sarah Eunkyung Kim	Farhang Yazdani	Haibo FAN	Cruise YANG	Cheng YANG	Hongbin SHI	E. Jan Vardaman	Ryo Takigawa Kai Takeuchi Yamaguchi Atsuya Yasuhiro Morikawa
13:55-15:20（Oral）	81, 245, 424, 436, 607	70, 129, 148, 152, 153, 284, 401	21, 56, 198, 210, 292, 497, 499	123, 146, 346, 359, 386, 481, 569	20, 62, 93, 134, 295, 567, 627	38, 125, 381, 391, 406, 492, 573	90, 96, 114, 137, 191, 194, 228	
15:20-16:00	**Poster Session B**							
Committee	Advanced Packaging&Packaging Materials & Processes	Packaging Materials & Processes	MEMS Packaging & Optoelectronics and New Display	RF Electronic Packaging	Emerging Technologies & Pkg. Materials & Processes	Quality & Reliability	Quality & Reliability & Interconnection Technology	/
16:00-18:25	Session A4-Thermal Management & Interface	Session B4-Materials for Process and Reliability	Session C4-MEMS、Sensor and IoT	Session D4-RF Filters & Electronic Packaging	Session E4-Emerging Packaging Technologies	Session F4-Reliability Testing and Modeling	Session G4-Reliability Prediction	Session H4-R10 Interactive Session
Chairs	Chi ZHANG, Shenglin MA	Haoran MA, Liang ZHANG	Gaowei XU Jintang SHANG	Nan WANG, Yue SUN	Yanhong TIAN, Daquan YU	Sha XU, Chuantao HOU	Zhengwei FAN, Yi ZHONG	Shaw Fong WONG, Qian Wang
16:00-16:25（Keynote）	Hua BAO	Wangyun LI	Daiki Nakaya	Yao CAI	Eu Poh Leng	Karsten Meier	Terry WU	Qian WANG James Kim Andrew Tay Shinya Takyu Qidong WANG
16:25-18:40 (Oral)	229, 485, 488, 536, 537, 578, 539, 541, 544, 626	22, 31, 52, 227, 352, 404, 440, 505, 515, 540	98, 192, 216, 220, 368, 428, 453, 580, 637	327, 466, 554, 555, 570, 611, 613, 634, 636	**Keynote: Guangbin DOU** 221, 258, 342, 378, 397, 418, 297, 390, 439	498, 9, 15, 42, 46, 95, 288, 389, 409, 410, 448	55, 306, 414, 512, 621, 144, 345, 551, 619	

OVERVIEW OF ICEP SPECIAL SESSION

Thursday, August 7th, 2025, 13:30-15:30 Room 8

ICEP SPECIAL SESSION
Chair: Dr. Junsha WANG*, ICEP 2026 Technical Program Committee, Meisei University, Japan*
Co-chair: Dr. Yasuhiro Morikawa*, ICEP 2026 General Chair, General of ULVAC Inc., Japan*

13:30-14:00	**Surface Activated Room Temperature Bonding for Heterogeneous Photonics Integration** ***Dr. Ryo Takigawa*** *Associate Professor, Kyushu University, Japan*
14:00-14:30	**Polysilazane-mediated Room Temperature Bonding for Electronics Packaging** ***Dr. Kai Takeuchi*** *Assistant Professor, Tohoku University, Japan*
14:30-15:00	**Acid Copper Plating Process for RDL Interposer** ***Mr. Yamaguchi Atsuya*** *R&D Center, Electronics Development Department, JCU CORPORATION, Japan*
15:00-15:30	**Application of Magnetic Neutral Loop Discharge Plasma in Deep Etching of Low-CTE Glass Substrate for Co-Packaged Optics** ***Dr. Yasuhiro Morikawa*** *Manager, ULVAC, Inc., Japan*
15:30-16:00	***Tea Break & Networking***

OVERVIEW OF IEEE EPS REGION 10 SESSION

Thursday, August 7th, 2025, 16:00-18:30 Room 8

IEEE EPS R10 INTERACTIVE SESSION
Chair: Dr. Shaw Fong WONG, IEEE EPS R10 Program Chair, Malaysia
Co-chair: Dr. Qian WANG, IEEE EPS Beijing Chapter, China

16:00-16:05	**Greeting**: ***Dr. Qian WANG*** *IEEE EPS Beijing Chapter Chair, Tsinghua University, China*
16:05-16:25	**Greeting:** ***Dr. Shaw Fong WONG*** *IEEE EPS R10 Program Chair, Malaysia*
16:25-16:50	**Exploring the Correlation Between Post-Die Bond Epoxy Void and Bond Line Thickness and other Factors on Power Packaging with Silver Sintered Epoxy** ***IEMT-Mr. James Kim*** *NXP Semiconductors, Korea*
16:50-17:15	**Thermal and Failure Analysis of Advanced Microelectronic Devices** ***EPTC-Prof. Andrew TAY*** *National University of Singapore, Singapore*
17:15-17:40	**A Novel Expansion Process Using Tape Expansion, Self-Assembly, and Tape Frozen Detachment Technique and Its application to Hybrid Bonding** ***ICSJ-Mr. Shinya Takyu*** *Assistant General Manager, LINTEC Corporation, Japan*
17:40-18:05	**Two-Phase In-Situ Thin Liquid Film Cooling for Computing Module** ***ICEPT-Dr. Qidong WANG*** *Director of Packaging and Integration R&D center of Institute of Microelectronics, Chinese Academy of Sciences, China*
18:05-18:30	**Q&A on EPS Programs**

OVERVIEW OF POSTER PRESENTATION SESSIONS

<table>
<tr><td colspan="16">Poster Session A
Wednesday, August 6th, 2025, 15:20-16:00</td></tr>
<tr><td colspan="2">Area1</td><td colspan="2">Area2</td><td colspan="2">Area3</td><td colspan="2">Area4</td><td colspan="2">Area5</td><td colspan="2">Area6</td><td colspan="2">Area7</td><td colspan="2">Area8</td></tr>
<tr><td colspan="2">**Session 1**
Advanced Packaging
Session 11
Emerging Technologies</td><td colspan="2">**Session 2**
Packaging Materials & Processes</td><td colspan="2">**Session 3**
Packaging Design & Modeling
Session 4
Interconnection Technologies</td><td colspan="2">**Session 5**
Advanced Manufacturing
Session 3
Packaging Design & Modeling</td><td colspan="2">**Session 6**
Quality & Reliability
Session 7
Power Electronics & Energy Electronics</td><td colspan="2">**Session 8**
Optoelectronics and New Display
Session 6
Quality & Reliability</td><td colspan="2">**Session 9**
MEMS, Sensors and IoT
Session 10
RF Electronic Packaging</td><td colspan="2">**Session 11&9**
Emerging Technologies & Emerging Technologies
Session 6
Quality & Reliability</td></tr>
<tr><td>68, 147, 197
215, 229, 241
249, 280, 281
293, 317, 323</td><td>78
79
161
230</td><td colspan="2">16, 66, 74, 75
91, 92, 118, 126
132, 149, 151
164, 184, 193
200, 204</td><td>23, 29, 84
116, 127
150, 169
189</td><td>33, 71, 82
231, 239
248, 251
272</td><td>44, 94
166, 171
234, 242
273, 421
463, 524</td><td>385, 396
398, 426
457, 490</td><td>12, 14, 18
19, 30, 37
41, 45, 53</td><td>11, 109
326, 348
581, 597
650</td><td>35, 183
269, 299
301, 304
388, 496
506, 508</td><td>54, 73
103, 110
120, 124</td><td>115, 117
156, 181
318, 336
339, 371
422, 467
534</td><td>237, 532
579, 602
614</td><td>236
565
566
217</td><td>133, 139
145, 157
174, 178
590, 604
612, 616
622, 659
665</td></tr>
<tr><td colspan="16">Poster Session B
Thursday, August 7th, 2025, 15:20-16:00</td></tr>
<tr><td colspan="2">**Session 1**
Advanced Packaging
Session 11
Emerging Technologies</td><td colspan="2">**Session 2**
Packaging Materials & Processes
Session 5
Advanced Manufacturing</td><td colspan="2">**Session 3**
Packaging Design & Modeling
Session 4
Interconnection Technologies</td><td colspan="2">**Session 3**
Packaging Design & Modeling
Session 6
Quality & Reliability</td><td colspan="2">**Session 6**
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Quality & Reliability
Session 8
Optoelectronics and New Display</td><td colspan="2">**Session 6**
Quality & Reliability</td><td colspan="2" rowspan="2">/</td></tr>
<tr><td>335, 367, 394
412, 420, 427
491, 518, 531
599, 615, 623</td><td>262
380
399
533</td><td>209, 214
233, 235
240, 256
266, 319
343, 357
374, 429
516</td><td>550
557
662</td><td>196, 201
218, 226
243, 283
353, 373</td><td>290, 337
340, 438
519, 600
638, 641</td><td>525, 538
548, 651</td><td>182, 185
203, 206
211, 212
252, 259
276, 277
296, 320</td><td colspan="2">321, 324, 325, 330
349, 354, 358, 377
382, 395, 402, 413
416, 417, 432, 493</td><td>433, 434
441, 449
456, 461
470, 478
487</td><td>545, 559
575, 585
631, 646
647</td><td colspan="2">503, 509, 529
542, 556, 568
589</td></tr>
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